- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels

description/ordering information

The SN74CBT3384A provides ten bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as two 5-bit switches with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the switch is on, and port A is connected to port B. When \overline{OE} is high, the switch is open, and the high-impedance state exists between the two ports.

DB, DBQ, DGV, DW, OR PW PACKAGE (TOP VIEW)

10E	1	U ₂₄	v _{cc}
1B1 [2	23	2B5
1A1 [3	22	2A5
1A2	4	21	2A4
1B2	5	20	2B4
1B3[6	19	2B3
1A3[7	18	2A3
1A4	8	17	2A2
1B4 [9	16	2B2
1B5 [10	15	2B1
1A5 [11	14	2A1
GND[12	13] 2 0E

ORDERING INFORMATION

T _A	PACKAGI	Εţ	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
	SOIC - DW	Tube	SN74CBT3384ADW	ODT0004A		
	SOIC - DW	Tape and reel	SN74CBT3384ADWR	CBT3384A		
	SSOP – DB	Tape and reel	SN74CBT3384ADBR	CU384A		
–40°C to 85°C	SSOP (QSOP) – DBQ	Tape and reel	SN74CBT3384ADBQR	CBT3384A		
	TOOOD DW	Tube	SN74CBT3384APW			
	TSSOP – PW	Tape and reel	SN74CBT3384APWR	CU384A		
	TVSOP – DGV	Tape and reel	SN74CBT3384ADGVR	CU384A		

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each 5-bit bus switch)

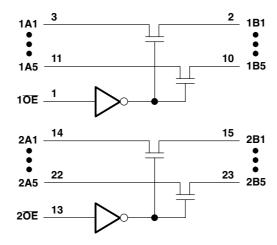
INP	UTS	INPUTS/OUTPUTS					
10E	2 OE	1B1-1B5	2B1-2B5				
L	L	1A1-1A5	2A1-2A5				
L	Н	1A1-1A5	Z				
Н	L	Z	2A1-2A5				
Н	Н	Z	Z				



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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		–0.5 V to 7 V
Continuous channel current		128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	DB package	63°C/W
	DBQ package	61°C/W
	DGV package	86°C/W
	DW package	46°C/W
	PW package	88°C/W
Storage temperature range, T _{sta}		-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	4	5.5	V
V_{IH}	High-level control input voltage	2		V
V_{IL}	Low-level control input voltage		8.0	V
T _A	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAI	RAMETER		TEST CONDITION	ONS	MIN	TYP†	MAX	UNIT	
V _{IK}		$V_{CC} = 4.5 \text{ V},$	$I_I = -18 \text{ mA}$				-1.2	V	
II		$V_{CC} = 5.5 \text{ V},$	$V_I = 5.5 \text{ V or GND}$				±1	μΑ	
Icc		$V_{CC} = 5.5 \text{ V},$	$I_{O} = 0$,	$V_I = V_{CC}$ or GND			3	μΑ	
Δl _{CC} [‡]	Control inputs	$V_{CC} = 5.5 \text{ V},$	One input at 3.4 V,	Other inputs at V _{CC} or GND			2.5	mA	
C _i	Control inputs	V _I = 3 V or 0				4		pF	
C _{io(OFF)}		$V_{O} = 3 \text{ V or } 0,$	OE = V _{CC}			4.5		pF	
		$V_{CC} = 4 \text{ V},$ TYP at $V_{CC} = 4 \text{ V}$	V _I = 2.4 V,	I _I = 15 mA		14	20		
r _{on} §			V 0	I _I = 64 mA		5	7	Ω	
		V _{CC} = 4.5 V	$V_I = 0$	I _I = 30 mA		5	7	7	
			$V_1 = 2.4 V$,	I _I = 15 mA		10	15		

 $^{^{\}dagger}$ All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO	V _{CC} = 4 V	V _{CC} = 5 V ± 0.5 V		UNIT
	(INPOT)	(OUTPUT)	MIN MAX	MIN	MAX	
t _{pd} ¶	A or B	B or A	0.35		0.25	ns
t _{en}	ŌĒ	A or B	6.2	1.9	5.7	ns
t _{dis}	ŌĒ	A or B	5.5	2.1	5.2	ns

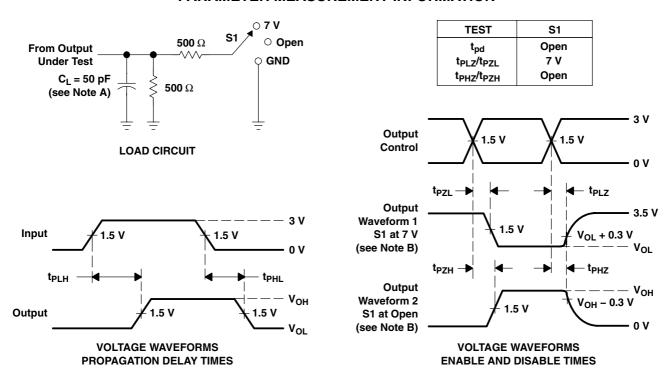
¹ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



[‡] This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
SN74CBT3384ADBQR	LIFEBUY	SSOP	DBQ	24	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CBT3384A	
SN74CBT3384ADBR	LIFEBUY	SSOP	DB	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU384A	
SN74CBT3384ADGVR	LIFEBUY	TVSOP	DGV	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU384A	
SN74CBT3384ADW	LIFEBUY	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3384A	
SN74CBT3384ADWR	LIFEBUY	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3384A	
SN74CBT3384APW	LIFEBUY	TSSOP	PW	24	60	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU384A	
SN74CBT3384APWR	LIFEBUY	TSSOP	PW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU384A	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION



TAPE DIMENSIONS WHO WE PI WHO WE PI WHO WE BO W Cavity AO AO Cavity Cavity Cavity AO Cavity Cavity

A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT3384ADBQR	SSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74CBT3384ADBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74CBT3384ADGVR	TVSOP	DGV	24	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74CBT3384ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74CBT3384APWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1



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*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT3384ADBQR	SSOP	DBQ	24	2500	356.0	356.0	35.0
SN74CBT3384ADBR	SSOP	DB	24	2000	356.0	356.0	35.0
SN74CBT3384ADGVR	TVSOP	DGV	24	2000	356.0	356.0	35.0
SN74CBT3384ADWR	SOIC	DW	24	2000	350.0	350.0	43.0
SN74CBT3384APWR	TSSOP	PW	24	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74CBT3384ADW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74CBT3384APW	PW	TSSOP	24	60	530	10.2	3600	3.5

DBQ (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



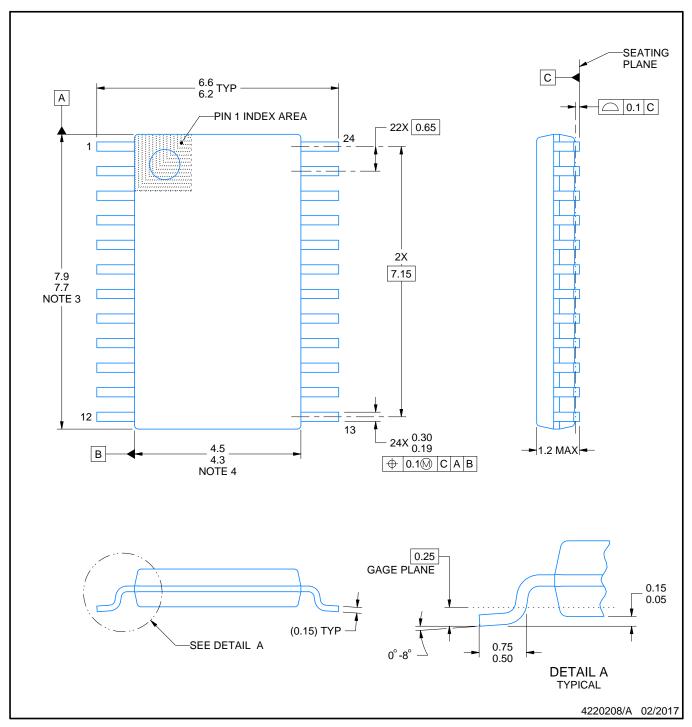
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
- D. Falls within JEDEC MO-137 variation AE.





SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

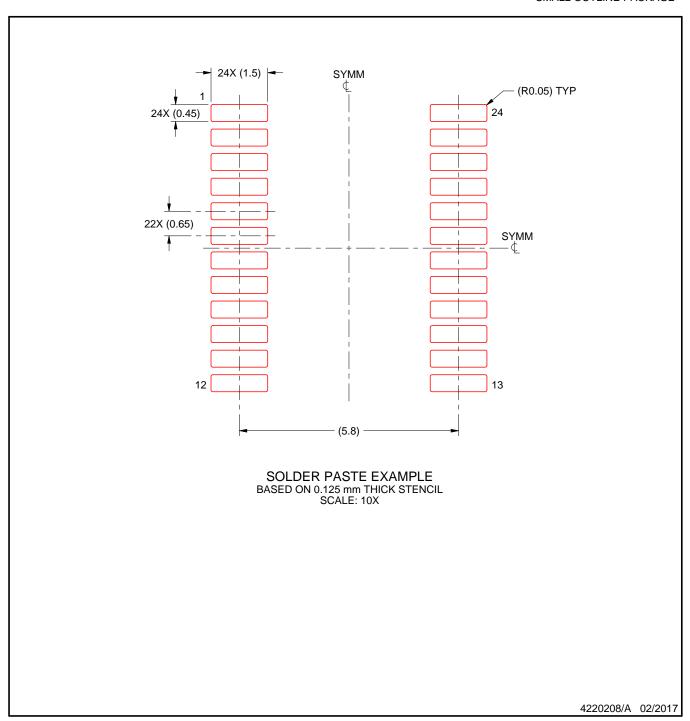


NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194 DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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